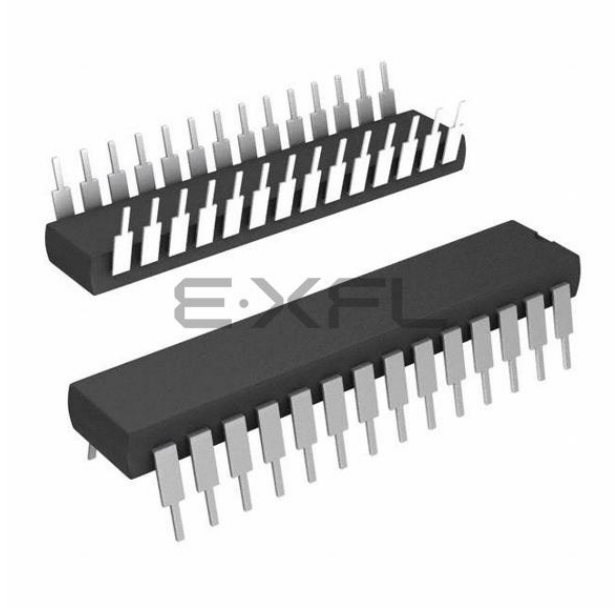
Microchip Technology - DSPIC33EV256GM002-I/SP Datasheet



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

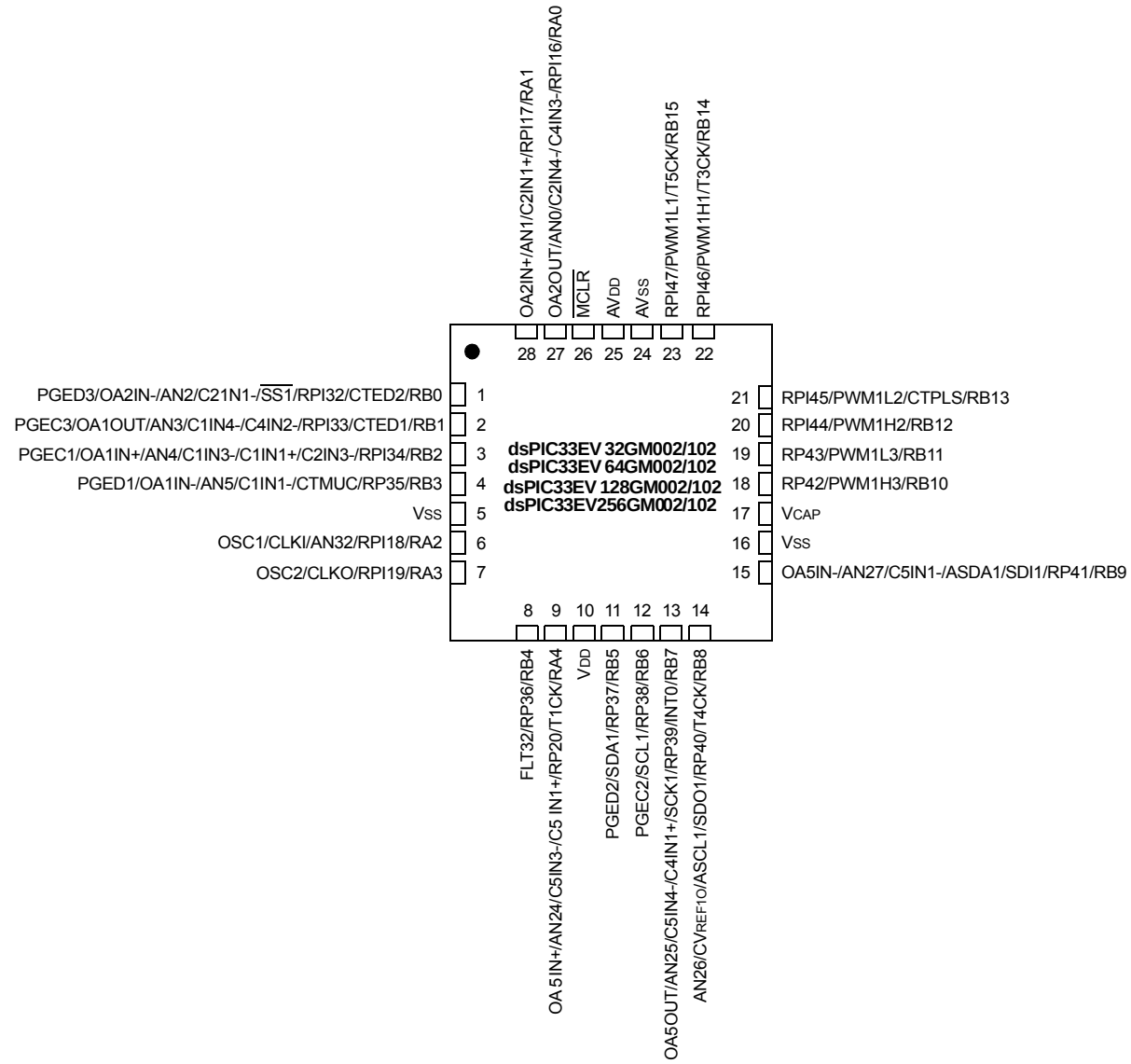
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 11x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev256gm002-i-sp

Pin Diagrams (Continued)

28-Pin QFN-S(1,2,3,4)



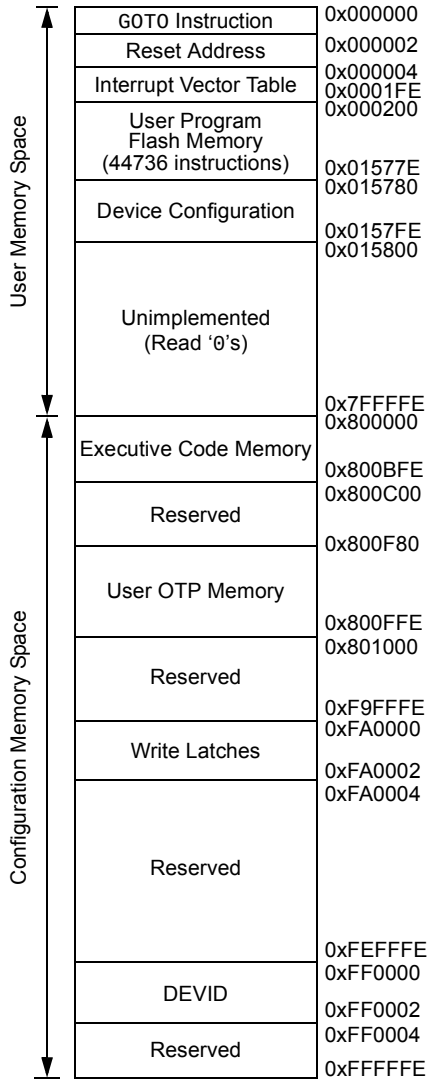
Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.5 "Peripheral Pin Select (PPS)"** for available peripherals and information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: If the op amp is selected when OPAEN (CMxCON<10>) = 1, the OAx input is used; otherwise, the ANx input is used.

4: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

FIGURE 4-3: PROGRAM MEMORY MAP FOR dsPIC33EV128GM00X/10X DEVICES(1)



Note 1: Memory areas are not shown to scale.

TABLE 4-3: INPUT CAPTURE 1 THROUGH INPUT CAPTURE 4 REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
IC1CON1	0140	—	—	ICSIDL	ICTSEL2	ICTSEL1	ICTSEL0	—	—	—	ICI1	ICI0	ICOV	ICBNE	ICM2	ICM1	ICM0	0000
IC1CON2	0142	—	—	—	—	—	—	—	IC32	ICTRIG	TRIGSTAT	—	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0	000D
IC1BUF	0144	Input Capture 1 Buffer Register																xxxx
IC1TMR	0146	Input Capture 1 Timer Register																0000
IC2CON1	0148	—	—	ICSIDL	ICTSEL2	ICTSEL1	ICTSEL0	—	—	—	ICI1	ICI0	ICOV	ICBNE	ICM2	ICM1	ICM0	0000
IC2CON2	014A	—	—	—	—	—	—	—	IC32	ICTRIG	TRIGSTAT	—	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0	000D
IC2BUF	014C	Input Capture 2 Buffer Register																xxxx
IC2TMR	014E	Input Capture 2 Timer Register																0000
IC3CON1	0150	—	—	ICSIDL	ICTSEL2	ICTSEL1	ICTSEL0	—	—	—	ICI1	ICI0	ICOV	ICBNE	ICM2	ICM1	ICM0	0000
IC3CON2	0152	—	—	—	—	—	—	—	IC32	ICTRIG	TRIGSTAT	—	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0	000D
IC3BUF	0154	Input Capture 3 Buffer Register																xxxx
IC3TMR	0156	Input Capture 3 Timer Register																0000
IC4CON1	0158	—	—	ICSIDL	ICTSEL2	ICTSEL1	ICTSEL0	—	—	—	ICI1	ICI0	ICOV	ICBNE	ICM2	ICM1	ICM0	0000
IC4CON2	015A	—	—	—	—	—	—	—	IC32	ICTRIG	TRIGSTAT	—	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0	000D
IC4BUF	015C	Input Capture 4 Buffer Register																xxxx
IC4TMR	015E	Input Capture 4 Timer Register																0000

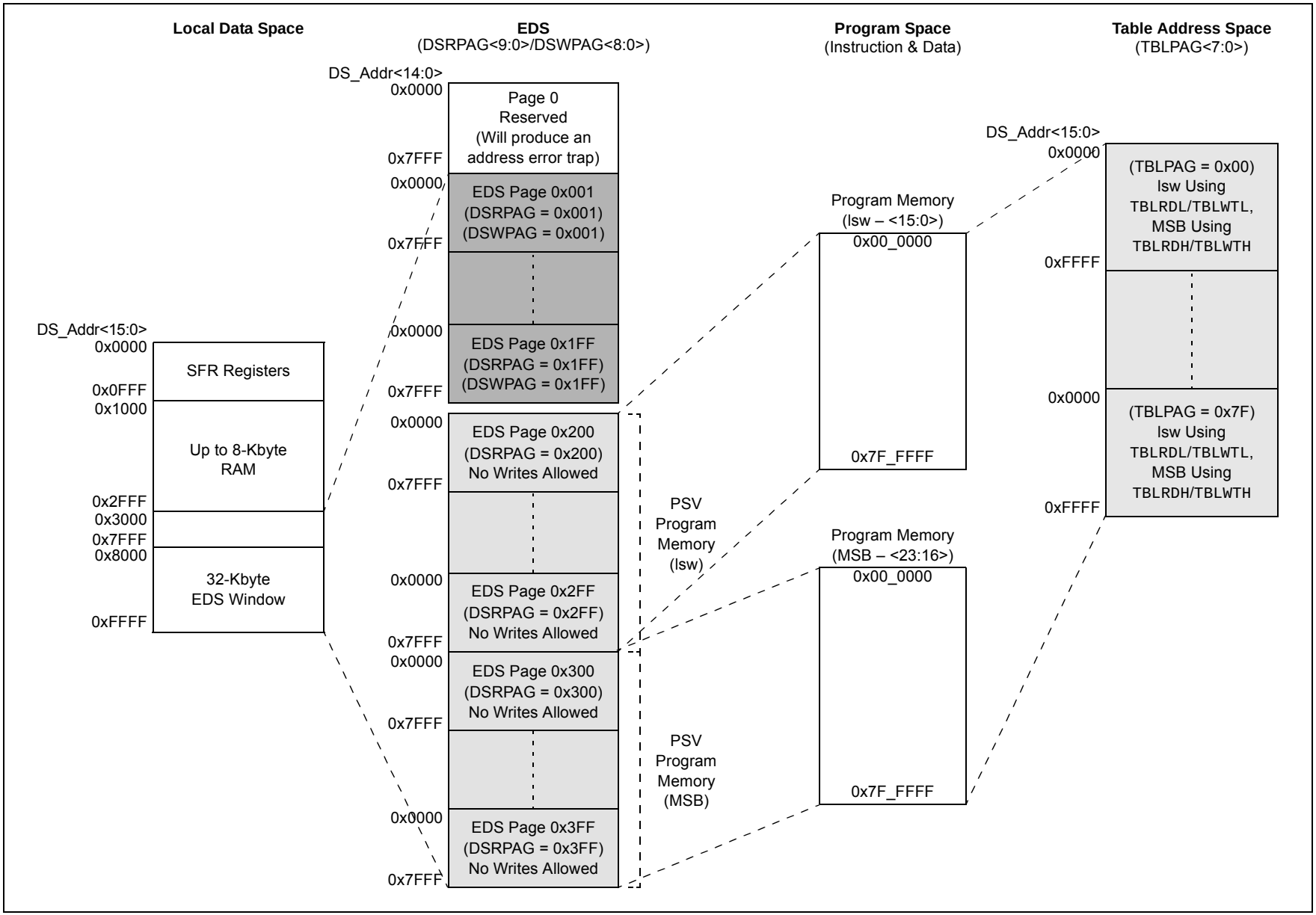
Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-4: I2C1 REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
I2C1CON1	0200	I2CEN	—	I2CSIDL	SCLREL	STRICT	A10M	DISSLW	SMEN	GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	1000
I2C1CON2	0202	—	—	—	—	—	—	—	—	—	PCIE	SCIE	BOEN	SDAHT	SBCDE	AHEN	DHEN	1000
I2C1STAT	0204	ACKSTAT	TRSTAT	ACKTIM	—	—	BCL	GCSTAT	ADD10	IWCOL	I2COV	D_A	P	S	R_W	RBF	TBF	0000
I2C1ADD	0206	—	—	—	—	—	—	I2C1 Address Register										0000
I2C1MSK	0208	—	—	—	—	—	—	I2C1 Address Mask Register										0000
I2C1BRG	020A	Baud Rate Generator Register																0000
I2C1TRN	020C	—	—	—	—	—	—	—	—	I2C1 Transmit Register								00FF
I2C1RCV	020E	—	—	—	—	—	—	—	—	I2C1 Receive Register								0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

FIGURE 4-11: PAGED DATA MEMORY SPACE



REGISTER 9-2: CLKDIV: CLOCK DIVISOR REGISTER(2)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1
ROI	DOZE2(3)	DOZE1(3)	DOZE0(3)	DOZEN(1,4)	FRCDIV2	FRCDIV1	FRCDIV0
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PLLPOST1	PLLPOST0	—	PLLPRE4	PLLPRE3	PLLPRE2	PLLPRE1	PLLPRE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ROI:** Recover on Interrupt bit
1 = Interrupts will clear the DOZEN bit
0 = Interrupts have no effect on the DOZEN bit

bit 14-12 **DOZE<2:0>:** Processor Clock Reduction Select bits(3)
111 = FCY divided by 128
110 = FCY divided by 64
101 = FCY divided by 32
100 = FCY divided by 16
011 = FCY divided by 8
010 = FCY divided by 4
001 = FCY divided by 2
000 = FCY divided by 1 (default)

bit 11 **DOZEN:** Doze Mode Enable bit(1,4)
1 = DOZE<2:0> field specifies the ratio between the peripheral clocks and the processor clocks
0 = Processor clock and peripheral clock ratio are forced to 1:1

bit 10-8 **FRCDIV<2:0>:** Internal Fast RC Oscillator Postscaler bits
111 = FRC divided by 256
110 = FRC divided by 64
101 = FRC divided by 32
100 = FRC divided by 16
011 = FRC divided by 8
010 = FRC divided by 4
001 = FRC divided by 2 (default)
000 = FRC divided by 1

bit 7-6 **PLLPOST<1:0>:** PLL VCO Output Divider Select bits (also denoted as 'N2', PLL postscaler)
11 = Output divided by 8
10 = Reserved
01 = Output divided by 4
00 = Output divided by 2

bit 5 **Unimplemented:** Read as '0'

Note 1: This bit is cleared when the ROI bit is set and an interrupt occurs.

2: This register resets only on a Power-on Reset (POR).

3: DOZE<2:0> bits can only be written to when the DOZEN bit is clear. If DOZEN = 1, any writes to DOZE<2:0> are ignored.

4: The DOZEN bit cannot be set if DOZE<2:0> = 000. If DOZE<2:0> = 000, any attempt by user software to set the DOZEN bit is ignored.

REGISTER 9-3: PLLFBD: PLL FEEDBACK DIVISOR REGISTER(1)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	PLLDIV8
bit 15							bit 8

R/W-0	R/W-0	R/W-1	R/W-1	R/W-0	R/W-0	R/W-0	R/W-0
PLLDIV<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as '0'

bit 8-0 **PLLDIV<8:0>:** PLL Feedback Divisor bits (also denoted as 'M', PLL multiplier)

111111111 = 513
•
•
•
000110000 = 50 (default)
•
•
•
000000010 = 4
000000001 = 3
000000000 = 2

Note 1: This register is reset only on a Power-on Reset (POR).

REGISTER 22-26: CxTRmnCON: CANx TX/RX BUFFER mn CONTROL REGISTER (m = 0,2,4,6; n = 1,3,5,7)

R/W-0	R-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
TXENn	TXABTn	TXLARBn	TXERRn	TXREQn	RTRENn	TXnPRI1	TXnPRI0
bit 15							bit 8

R/W-0	R-0	R-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
TXENm	TXABTm(1)	TXLARBm(1)	TXERRm(1)	TXREQm	RTRENm	TXmPRI1	TXmPRI0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 See Definition for bits 7-0, controls Buffer n.

bit 7 **TXENm:** TX/RX Buffer Selection bit
1 = Buffer, TRBm, is a transmit buffer
0 = Buffer, TRBm, is a receive buffer

bit 6 **TXABTm:** Message Aborted bit(1)
1 = Message was aborted
0 = Message completed transmission successfully

bit 5 **TXLARBm:** Message Lost Arbitration bit(1)
1 = Message lost arbitration while being sent
0 = Message did not lose arbitration while being sent

bit 4 **TXERRm:** Error Detected During Transmission bit(1)
1 = A bus error occurred while the message was being sent
0 = A bus error did not occur while the message was being sent

bit 3 **TXREQm:** Message Send Request bit
1 = Requests that a message be sent; the bit automatically clears when the message is successfully sent
0 = Clearing the bit to '0' while set requests a message abort

bit 2 **RTRENm:** Auto-Remote Transmit Enable bit
1 = When a remote transmit is received, TXREQ will be set
0 = When a remote transmit is received, TXREQ will be unaffected

bit 1-0 **TXmPRI<1:0>:** Message Transmission Priority bits
11 = Highest message priority
10 = High intermediate message priority
01 = Low intermediate message priority
00 = Lowest message priority

Note 1: This bit is cleared when TXREQm is set.

Note: The buffers, SID, EID, DLC, Data Field and Receive Status registers, are located in DMA RAM.

25.0 OP AMP/COMPARATOR MODULE

Note 1: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Op Amp/Comparator"** (DS70000357) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

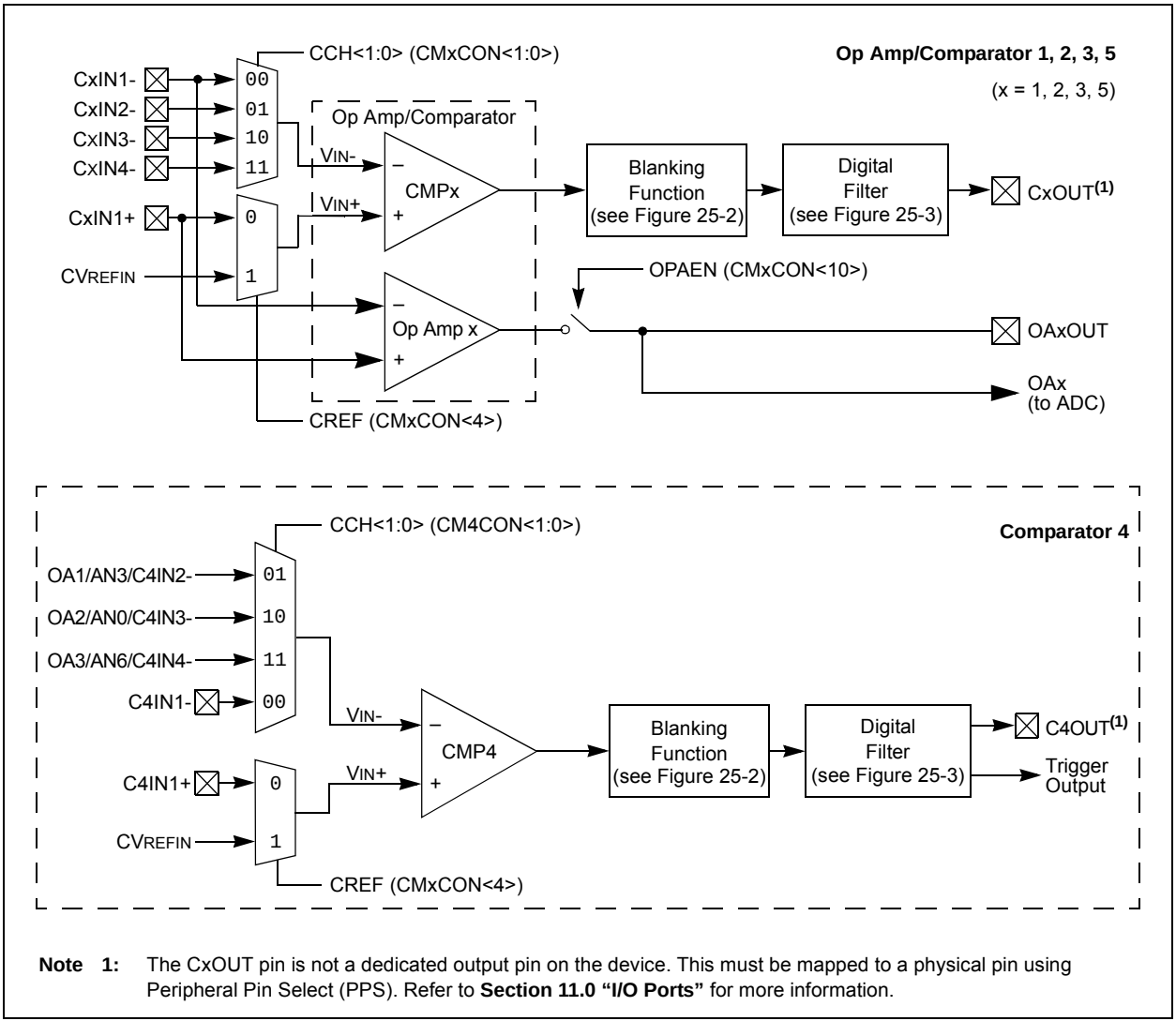
The dsPIC33EVXXXGM00X/10X family devices contain up to five comparators that can be configured in various ways. CMP1, CMP2, CMP3 and CMP5 also have the option to be configured as op amps, with the output being brought to an external pin for gain/filtering connections. As shown in Figure 25-1, individual comparator options are specified by the comparator module's Special Function Register (SFR) control bits.

The following options allow users to:

- Select the Edge for Trigger and Interrupt Generation
- Configure the Comparator Voltage Reference
- Configure Output Blanking and Masking
- Configure as a Comparator or Op Amp (CMP1, CMP2, CMP3 and CMP5 only)

Note: Not all op amp/comparator input/output connections are available on all devices. See the **"Pin Diagrams"** section for available connections.

FIGURE 25-1: OP AMP/COMPARATOR x MODULE BLOCK DIAGRAM



Note 1: The CxOUT pin is not a dedicated output pin on the device. This must be mapped to a physical pin using Peripheral Pin Select (PPS). Refer to **Section 11.0 "I/O Ports"** for more information.

REGISTER 25-2: CMxCON: COMPARATOR x CONTROL REGISTER (x = 1, 2, 3 OR 5)

R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R-0
CON	COE	CPOL	—	—	OPAEN(2)	CEVT	COUT
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0
EVPOL1(3)	EVPOL0(3)	—	CREF(1)	—	—	CCH1(1)	CCH0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CON:** Op Amp/Comparator x Enable bit
1 = Op Amp/Comparator x is enabled
0 = Op Amp/Comparator x is disabled

bit 14 **COE:** Comparator x Output Enable bit
1 = Comparator output is present on the CxOUT pin
0 = Comparator output is internal only

bit 13 **CPOL:** Comparator x Output Polarity Select bit
1 = Comparator output is inverted
0 = Comparator output is not inverted

bit 12-11 **Unimplemented:** Read as '0'

bit 10 **OPAEN:** Op Amp x Enable bit(2)
1 = Op Amp x is enabled
0 = Op Amp x is disabled

bit 9 **CEVT:** Comparator x Event bit
1 = Comparator event, according to EVPOL<1:0> settings, occurred; disables future triggers and interrupts until the bit is cleared
0 = Comparator event did not occur

bit 8 **COUT:** Comparator x Output bit
When CPOL = 0 (non-inverted polarity):
1 = VIN+ > VIN-
0 = VIN+ < VIN-
When CPOL = 1 (inverted polarity):
1 = VIN+ < VIN-
0 = VIN+ > VIN-

Note 1: Inputs that are selected and not available will be tied to VSS. See the **"Pin Diagrams"** section for available inputs for each package.

2: The op amp and the comparator can be used simultaneously in these devices. The OPAEN bit only enables the op amp while the comparator is still functional.

3: After configuring the comparator, either for a high-to-low or low-to-high COUT transition (EVPOL<1:0> (CMxCON<7:6>) = 10 or 01), the Comparator x Event bit, CEVT (CMxCON<9>), and the Comparator Interrupt Flag, CMPIF (IFS1<2>), must be cleared before enabling the Comparator Interrupt Enable bit, CMPIE (IEC1<2>).

TABLE 27-2: dsPIC33EVXXXGM00X/10X CONFIGURATION BITS DESCRIPTION (CONTINUED)

Bit Field	Register	Description
OSCIOFNC	FOSC	OSC2 Pin Function bit (except in XT and HS modes) 1 = OSC2 is the clock output 0 = OSC2 is the general purpose digital I/O pin
IOL1WAY	FOSC	Peripheral Pin Select Configuration bit 1 = Allows only one reconfiguration 0 = Allows multiple reconfigurations
FCKSM<1:0>	FOSC	Clock Switching Mode bits 1x = Clock switching is disabled, Fail-Safe Clock Monitor is disabled 01 = Clock switching is enabled, Fail-Safe Clock Monitor is disabled 00 = Clock switching is enabled, Fail-Safe Clock Monitor is enabled
PLLKEN	FOSC	PLL Lock Wait Enable bit 1 = Clock switches to the PLL source; will wait until the PLL lock signal is valid 0 = Clock switch will not wait for PLL lock
WDTPS<3:0>	FWDT	Watchdog Timer Postscaler bits 1111 = 1:32,768 1110 = 1:16,384 • • • 0001 = 1:2 0000 = 1:1
WDTPRE	FWDT	Watchdog Timer Prescaler bit 1 = 1:128 0 = 1:32
FWDTEN<1:0>	FWDT	Watchdog Timer Enable bits 11 = WDT is enabled in hardware 10 = WDT is controlled through the SWDTEN bit 01 = WDT is enabled only while device is active and disabled in Sleep; the SWDTEN bit is disabled 00 = WDT and the SWDTEN bit are disabled
WINDIS	FWDT	Watchdog Timer Window Enable bit 1 = Watchdog Timer is in Non-Window mode 0 = Watchdog Timer is in Window mode
WDTWIN<1:0>	FWDT	Watchdog Timer Window Select bits 11 = WDT window is 25% of WDT period 10 = WDT window is 37.5% of WDT period 01 = WDT window is 50% of WDT period 00 = WDT window is 75% of WDT period
BOREN	FPOR	Brown-out Reset (BOR) Detection Enable bit 1 = BOR is enabled 0 = BOR is disabled
ICS<1:0>	FICD	ICD Communication Channel Select bits 11 = Communicates on PGEC1 and PGED1 10 = Communicates on PGEC2 and PGED2 01 = Communicates on PGEC3 and PGED3 00 = Reserved, do not use
DMTIVT<15:0>	FDMTINTVL	Lower 16 Bits of 32-Bit Field that Configures the DMT Window Interval bits
DMTIVT<31:16>	FDMTINTVH	Upper 16 Bits of 32-Bit Field that Configures the DMT Window Interval bits
DMTCNT<15:0>	FDMTCNTL	Lower 16 Bits of 32-Bit Field that Configures the DMT Instruction Count Time-out Value bits

28.0 INSTRUCTION SET SUMMARY

Note: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

The dsPIC33EV instruction set is almost identical to that of the dsPIC30F and dsPIC33F.

Most instructions are a single program memory word (24 bits). Only three instructions require two program memory locations.

Each single-word instruction is a 24-bit word, divided into an 8-bit opcode, which specifies the instruction type and one or more operands, which further specify the operation of the instruction.

The instruction set is highly orthogonal and is grouped into following five basic categories:

- Word or byte-oriented operations
- Bit-oriented operations
- Literal operations
- DSP operations
- Control operations

Table 28-1 lists the general symbols used in describing the instructions.

The dsPIC33E instruction set summary in Table 28-2 lists all the instructions, along with the Status Flags affected by each instruction.

Most word or byte-oriented W register instructions (including barrel shift instructions) have the following three operands:

- The first source operand, which is typically a register 'Wb' without any address modifier
- The second source operand, which is typically a register 'Ws' with or without an address modifier
- The destination of the result, which is typically a register 'Wd' with or without an address modifier

However, word or byte-oriented file register instructions have two operands:

- The file register specified by the value 'f'
- The destination, which could be either the file register 'f' or the W0 register, which is denoted as 'WREG'

Most bit-oriented instructions (including simple rotate/shift instructions) have two operands:

- The W register (with or without an address modifier) or file register (specified by the value of 'Ws' or 'f')
- The bit in the W register or file register (specified by a literal value or indirectly by the contents of register 'Wb')

The literal instructions that involve data movement can use some of the following operands:

- A literal value to be loaded into a W register or file register (specified by 'k')
- The W register or file register where the literal value is to be loaded (specified by 'Wb' or 'f')

However, literal instructions that involve arithmetic or logical operations use some of the following operands:

- The first source operand, which is a register 'Wb' without any address modifier
- The second source operand, which is a literal value
- The destination of the result (only if not the same as the first source operand), which is typically a register 'Wd' with or without an address modifier

The MAC class of DSP instructions can use some of the following operands:

- The accumulator (A or B) to be used (required operand)
- The W registers to be used as the two operands
- The X and Y address space prefetch operations
- The X and Y address space prefetch destinations
- The accumulator write-back destination

The other DSP instructions do not involve any multiplication and can include:

- The accumulator to be used (required)
- The source or destination operand (designated as Wso or Wdo, respectively) with or without an address modifier
- The amount of shift specified by a W register 'Wn' or a literal value

The control instructions can use some of the following operands:

- A program memory address
- The mode of the Table Read and Table Write instructions

FIGURE 30-17: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING CHARACTERISTICS

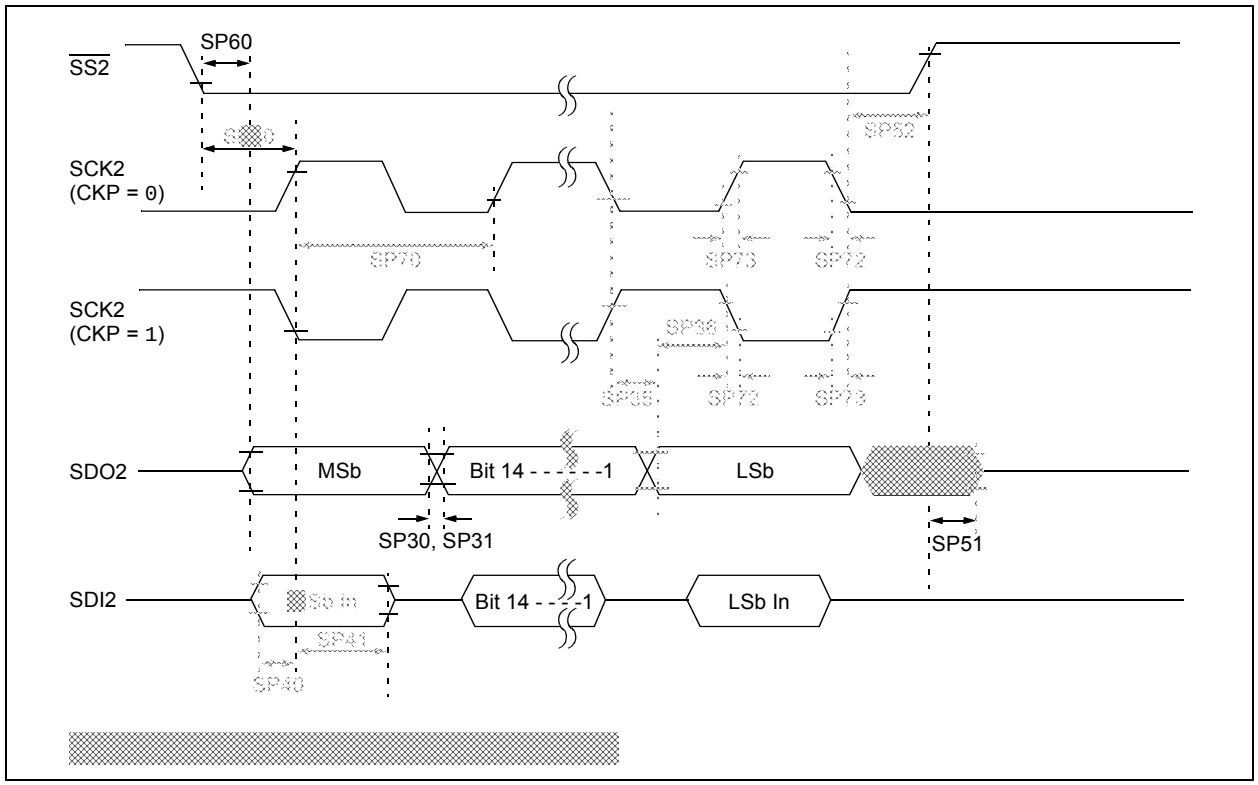


FIGURE 30-32: CANx MODULE I/O TIMING CHARACTERISTICS

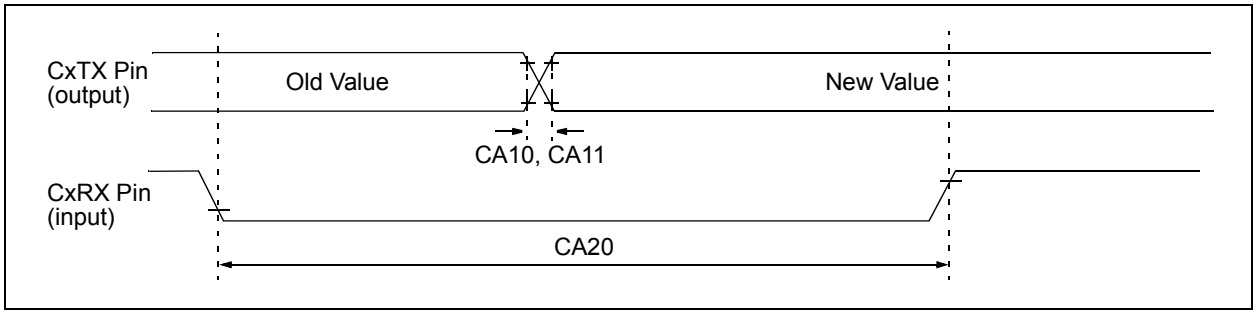


TABLE 30-48: CANx MODULE I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
CA10	TIOF	Port Output Fall Time	—	—	—	ns	See Parameter DO32
CA11	TIOR	Port Output Rise Time	—	—	—	ns	See Parameter DO31
CA20	TCWF	Pulse Width to Trigger CAN Wake-up Filter	120	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ." column is at 5.0V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 30-33: UARTx MODULE I/O TIMING CHARACTERISTICS

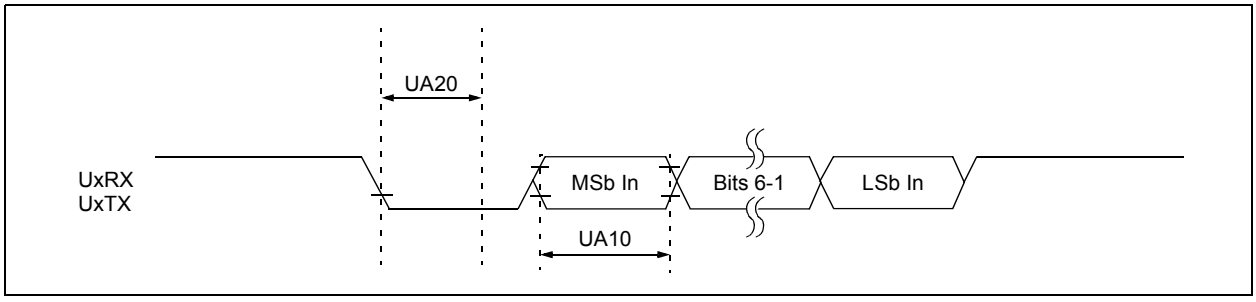


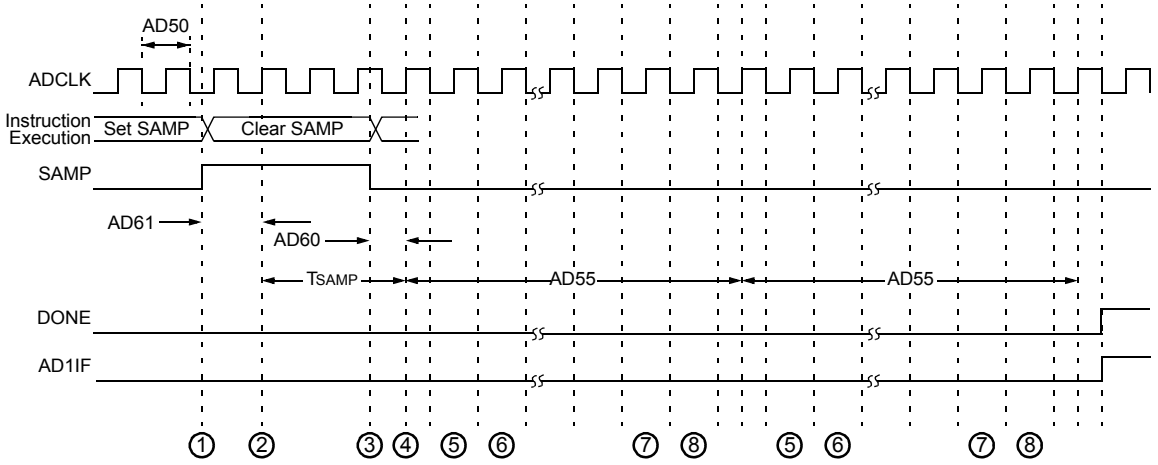
TABLE 30-49: UARTx MODULE I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
UA10	TUABAUD	UARTx Baud Time	66.67	—	—	ns	
UA11	FBAUD	UARTx Baud Frequency	—	—	15	Mbps	
UA20	TCWF	Start Bit Pulse Width to Trigger UARTx Wake-up	500	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ." column is at 5.0V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 30-35: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 0, SSRC<2:0> = 000, SSRCG = 0)



① – Software sets ADxCON1. SAMP to start sampling.

② – Sampling starts after discharge period. TSAMP is described in **"Analog-to-Digital Converter (ADC)"** (DS70621) of the *"dsPIC33/PIC24 Family Reference Manual"*.

③ – Software clears ADxCON1. SAMP to start conversion.

④ – Sampling ends, conversion sequence starts.

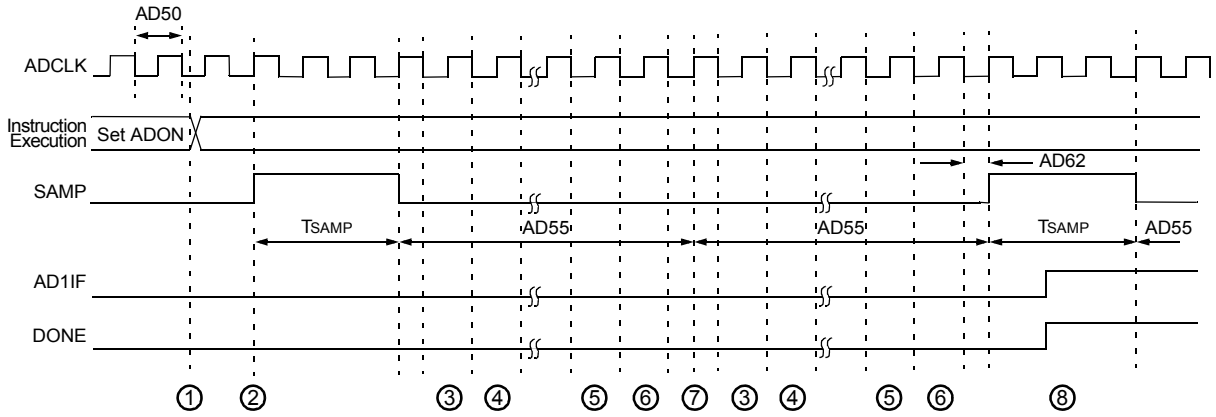
⑤ – Convert bit 9.

⑥ – Convert bit 8.

⑦ – Convert bit 0.

⑧ – One TAD for end of conversion.

FIGURE 30-36: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 1, SSRC<2:0> = 111, SSRCG = 0, SAMC<4:0> = 00010)



① – Software sets ADxCON1. ADON to start ADC operation.

② – Sampling starts after discharge period. TSAMP is described in **"Analog-to-Digital Converter (ADC)"** (DS70621) of the *"dsPIC33/PIC24 Family Reference Manual"*.

③ – Convert bit 9.

④ – Convert bit 8.

⑤ – Convert bit 0.

⑥ – One TAD for end of conversion.

⑦ – Begin conversion of next channel.

⑧ – Sample for time specified by SAMC<4:0>.

TABLE 30-58: ADC CONVERSION (10-BIT MODE) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions (see Note 1): 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(4)**	**Max.**	**Units**	**Conditions**
Clock Parameters							
AD50	TAD	ADC Clock Period	75	—	—	ns	
AD51	tRC	ADC Internal RC Oscillator Period	—	250	—	ns	
Conversion Rate							
AD55	tCONV	Conversion Time	—	12	—	TAD	
AD56	FCNV	Throughput Rate	—	—	1.1	Msps	Using simultaneous sampling
AD57a	TSAMP	Sample Time When Sampling Any ANx Input	2	—	—	TAD	
AD57b	TSAMP	Sample Time When Sampling the Op Amp Outputs	4	—	—	TAD	
Timing Parameters							
AD60	tPCS	Conversion Start from Sample Trigger(2)	2	—	3	TAD	Auto-convert trigger is not selected
AD61	tPSS	Sample Start from Setting Sample (SAMP) bit(2)	2	—	3	TAD	
AD62	tCSS	Conversion Completion to Sample Start (ASAM = 1)(2)	—	0.5	—	TAD	
AD63	tDPU	Time to Stabilize Analog Stage from ADC Off to ADC On(2)	—	—	20	μs	See **Note 3**

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but is not characterized. Analog modules: ADC, op amp/comparator and comparator voltage reference, will have degraded performance. Refer to Parameter BO10 in Table 30-12 for the minimum and maximum BOR values.

2: Because the sample caps will eventually lose charge, clock rates below 10 kHz may affect linearity performance, especially at elevated temperatures.

3: The parameter, tDPU, is the time required for the ADC module to stabilize at the appropriate level when the module is turned on (ADON (ADxCON1<15>) = 1). During this time, the ADC result is indeterminate.

4: These parameters are characterized but not tested in manufacturing.

TABLE 30-59: DMA MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS		Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
DM1	DMA Byte/Word Transfer Latency	1 TCY(2)	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Because DMA transfers use the CPU data bus, this time is dependent on other functions on the bus.

32.2 IIDLE

FIGURE 32-7: TYPICAL/MAXIMUM IIDLE vs. FOSC (EC MODE 10 MHz TO 70 MHz, 5.5V MAX)

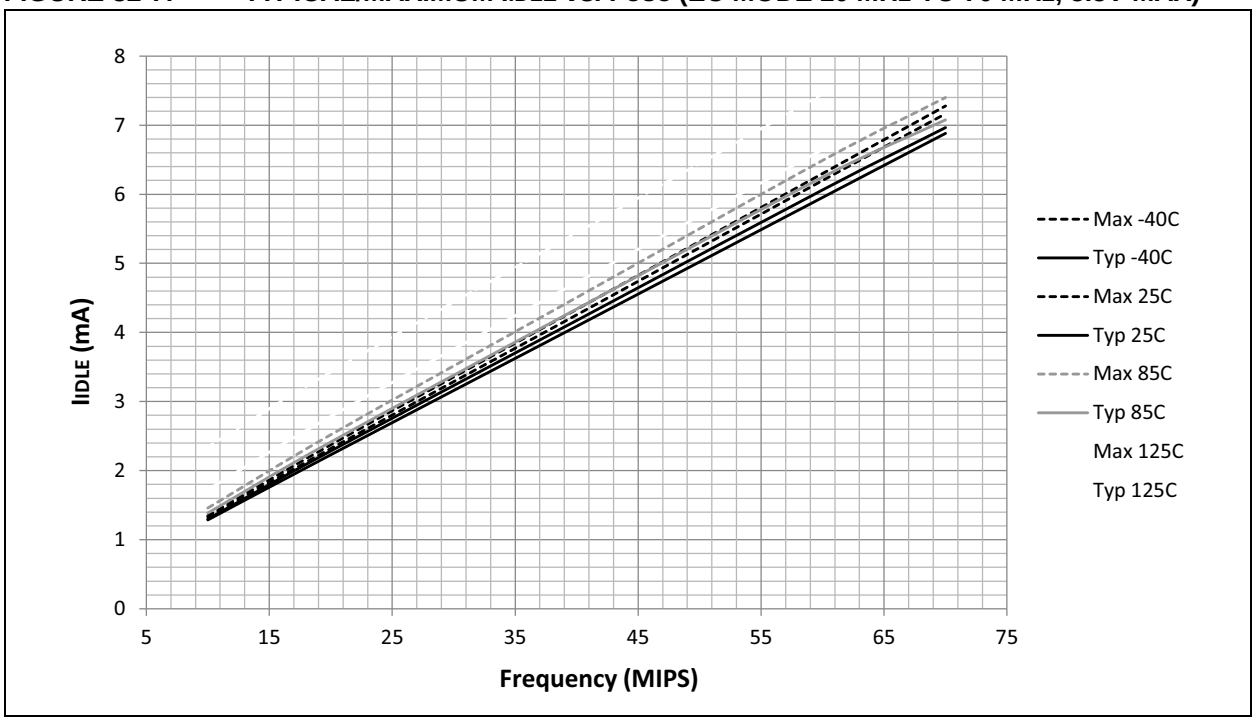
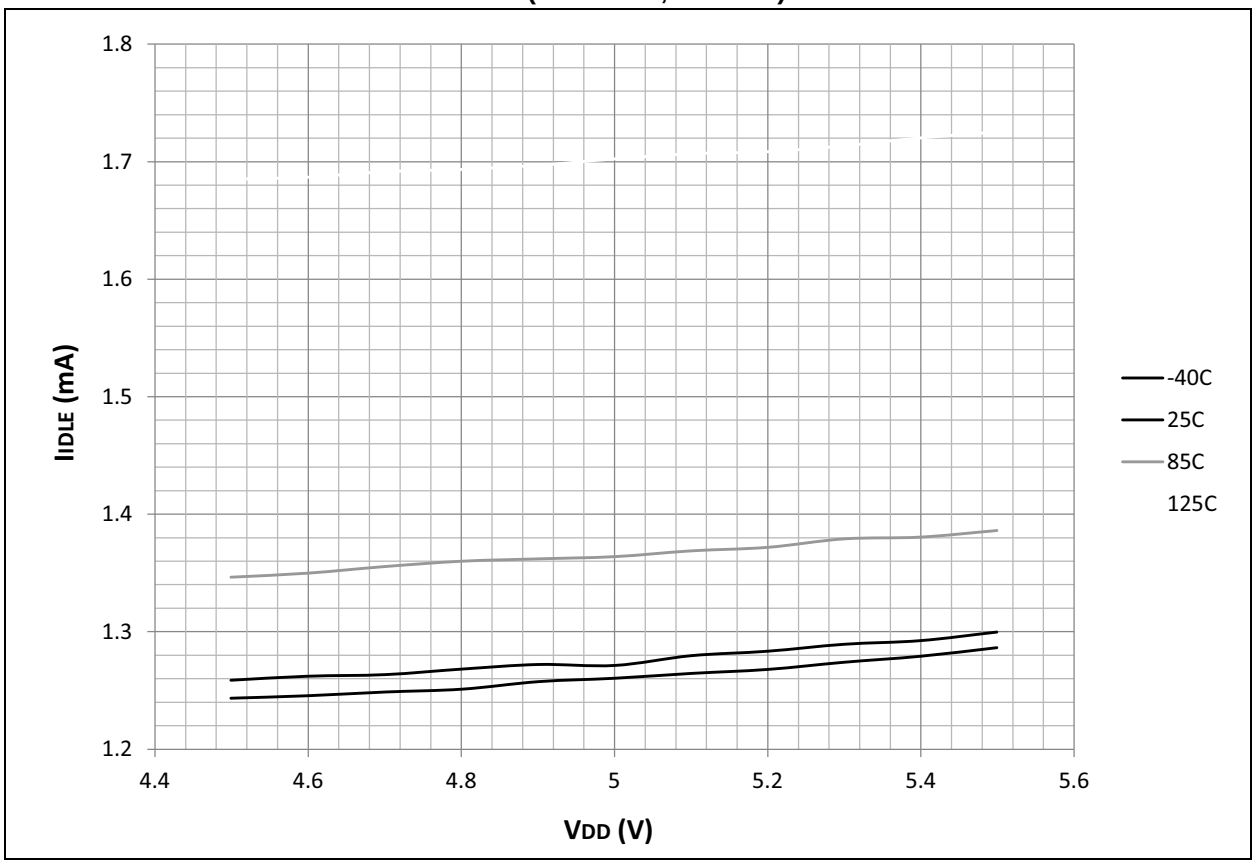


FIGURE 32-8: TYPICAL IIDLE vs. VDD (EC MODE, 10 MIPS)



33.14 Comparator Op Amp Offset

FIGURE 33-33: TYPICAL COMPARATOR OFFSET vs. VCM

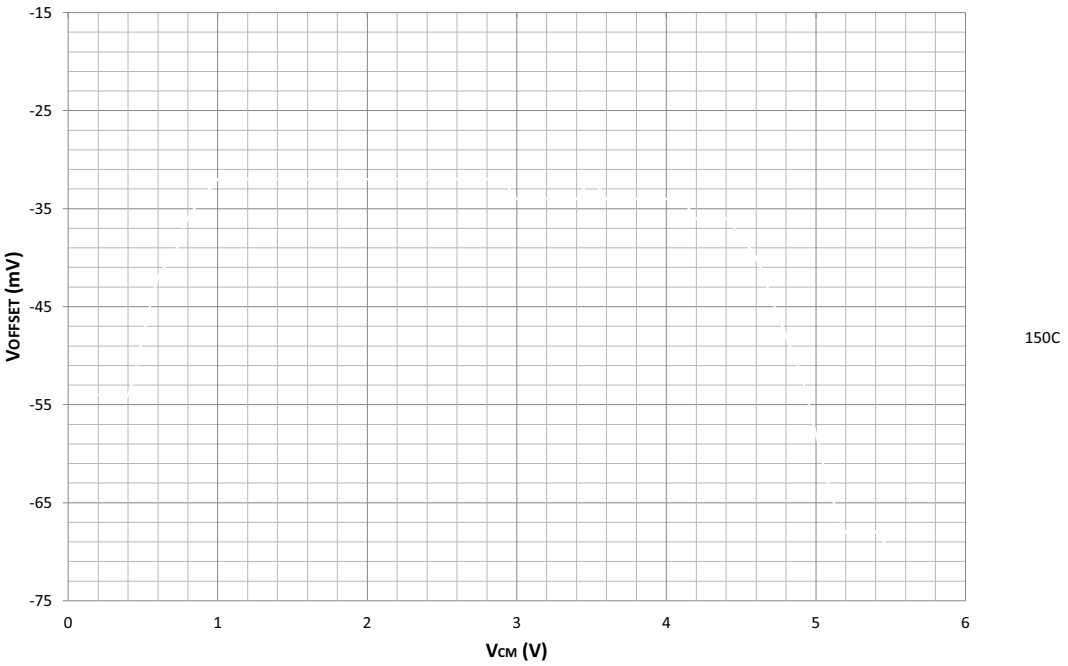
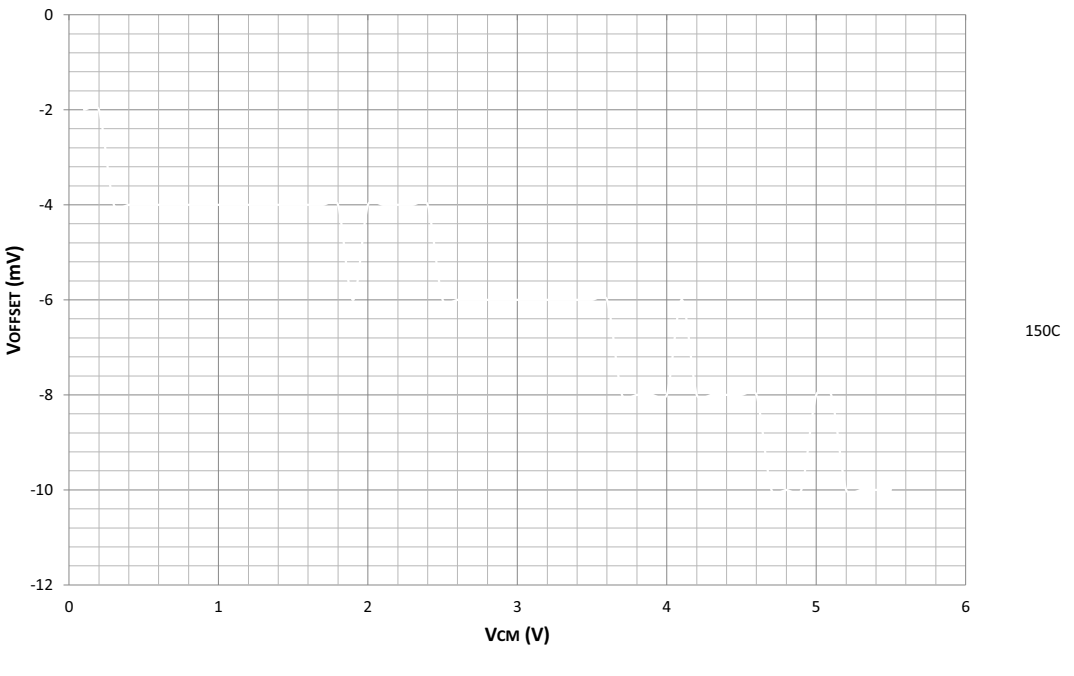
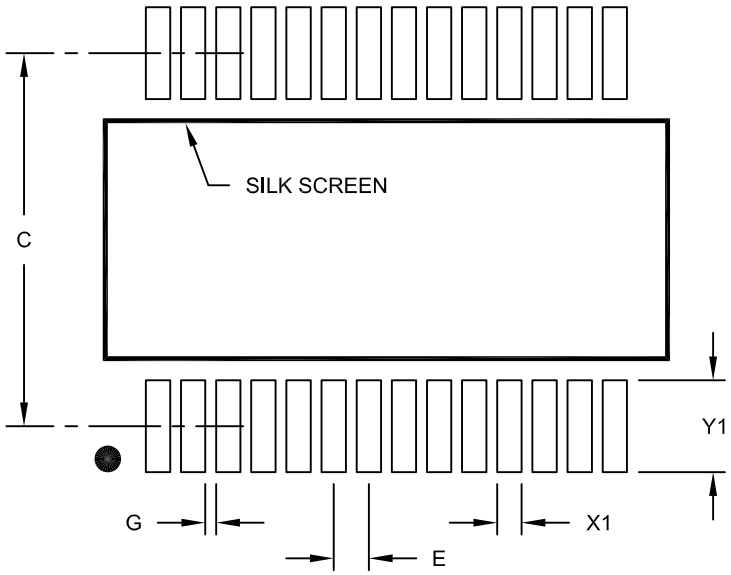


FIGURE 33-34: TYPICAL OP AMP OFFSET vs. VCM



28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Contact Pad Spacing	C		7.20	
Contact Pad Width (X28)	X1			0.45
Contact Pad Length (X28)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2073A

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.

QUALITY MANAGEMENT SYSTEM
CERTIFIED BY DNV
═ ISO/TS 16949 ═

Trademarks

ISBN: 978-1-5224-0975-5